

ASSEMBLY BUILD SHEET

CUSTOMER CONTACT INFORMATION

S.O. #: _____

Company: _____ Customer Name: _____ Rev: _____
Date: _____ Sales Contact QP: _____
Phone: _____ E-mail: _____
Fax: _____
P.O. #: _____

Is this item under the jurisdiction of the International Traffic in Arms Regulations (ITAR)? ☐ Yes ☐ No

If yes, what is the USML classification? _____

DELIVERY REQUEST

3 Days ☐ 2 Days ☐
1 Day (EXPEDITED) ☐ 8 Hours (EXPEDITED) ☐

See page 2 for shipping instructions

DEVICE INFORMATION

Device Name: _____
LOT #: _____
Wafer #(s): _____
Quantity of Devices to be Assembled: _____
Package Type: _____
Pin Count: _____
Body Size: _____
Lead Pitch: _____
Solder Ball Size: _____

DIE INFORMATION

Metalization (check one): ☐ Aluminum ☐ Gold ☐ Other (Specify)
Die Size: _____ X _____ **μm** or mils
Pad Pitch: _____ **μm** or mils
Die Pad Dimensions: _____ X _____ **μm** or mils
Die Pad Opening: _____ X _____ **μm** or mils
Thickness
μm: _____ mils: _____
Passivated: _____ Unpassivated: _____
Probed: _____ Unprobed: _____

SPECIAL INSTRUCTIONS

ASSEMBLY FLOW

☐ Electronic File (Cad File) ☐ Bonding Diagram Included

Die Pick: _____ Quantity of Die _____ Center of Wafer _____ Map Included _____

Die Attach: _____ Conductive Epoxy (QMI529HT)* _____ High Thermally/Electrically Conductive Material
_____ Non-Conductive Epoxy(QMI538NB)* _____ Thermally Conductive/Electrically Non-Conductive Material

Gold Wire Diameter: _____ 0.7 mil _____ 1.0 mil* _____ 1.3 mil _____ 2.0 mil
_____ 0.8 mil _____ 1.2 mil _____ 1.5 mil _____ Other (Al and Cu available call for wire sizes)

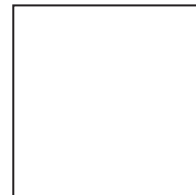
Heavy Wire: _____ 5 mil _____ 10 mil _____ 15mil _____ 20mil

*Standard Material: other options may add cost and leadtime

Seal: ☐ Standard Full Encapsulation (Glop Top) ☐ Encapsulation Around Leads Only
 ☐ Remolded / Flattened (Jedec std.) ☐ Frame & Lid (For Non-Solder Applications)
 ☐ None ☐ Removable Lid (For Walled Packages)
 ☐ Clear encapsulant (UV Cure) ☐ Epoxy on Corners 4,3 or 2
 ☐ Other (Specify) _____ ☐ Taped on Lids
 ☐ Epoxy Seal Lid

Marking: ☐ Pad Print (E-mail artwork in native .EPS or .AI file format)
 ☐ Hand Mark (Maximum 3 characters) _____
 ☐ None

Reject Parts ☐ Return to Customer ☐ Bag and Tag ☐ Destroy
Disposition:



Please indicate
how marking
should appear
on package
relative to pin 1.

*Unless otherwise noted all extra materials will be returned

SHIPPING INSTRUCTIONS:

Ship Instructions for Finished Product:

ATTN: _____

ADDRESS: _____

PHONE: _____

Ship Instructions for Remaining excess Die and Material:

ATTN: _____

ADDRESS: _____

PHONE: _____